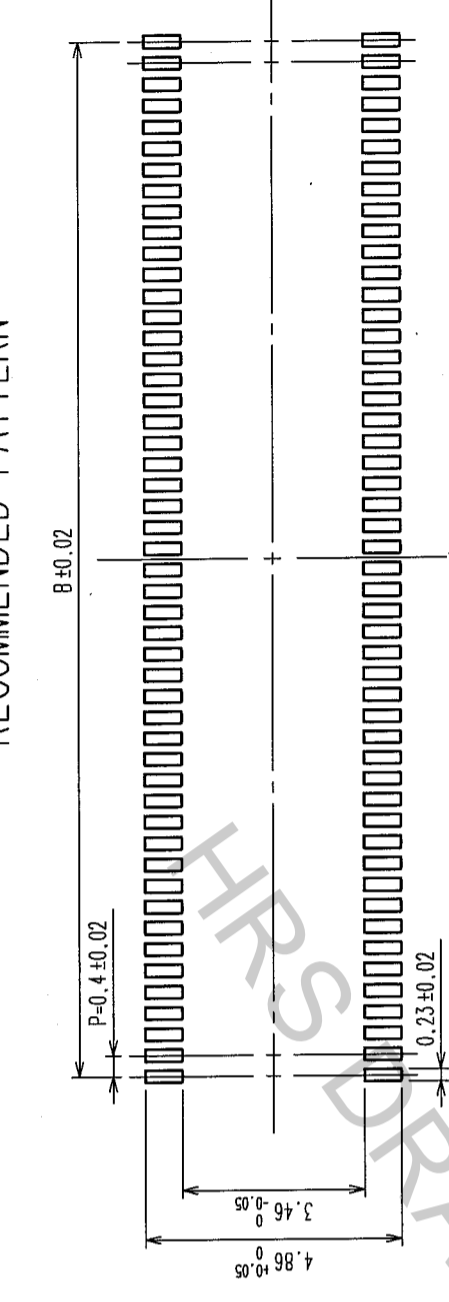
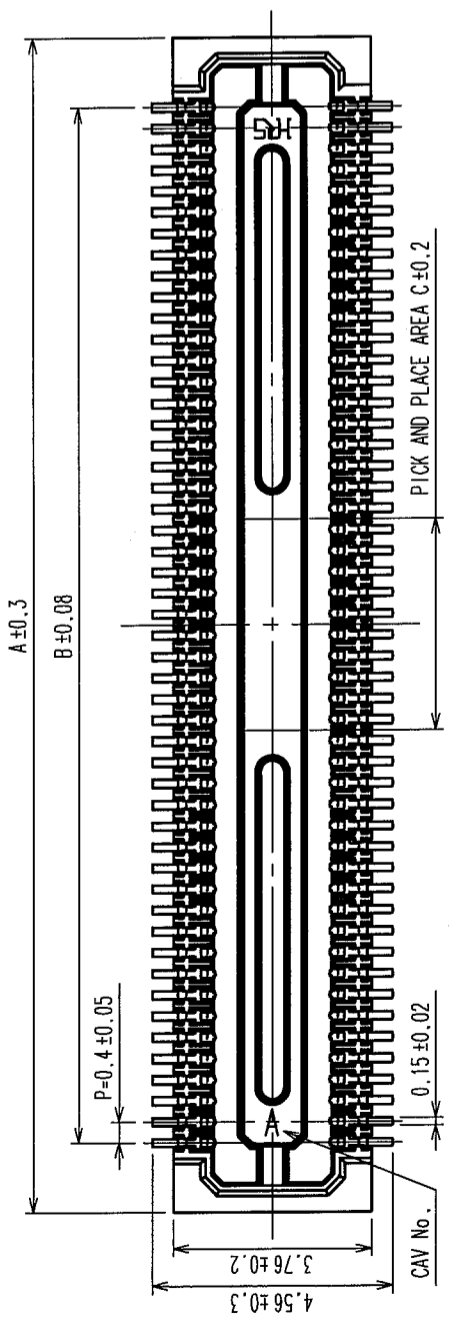
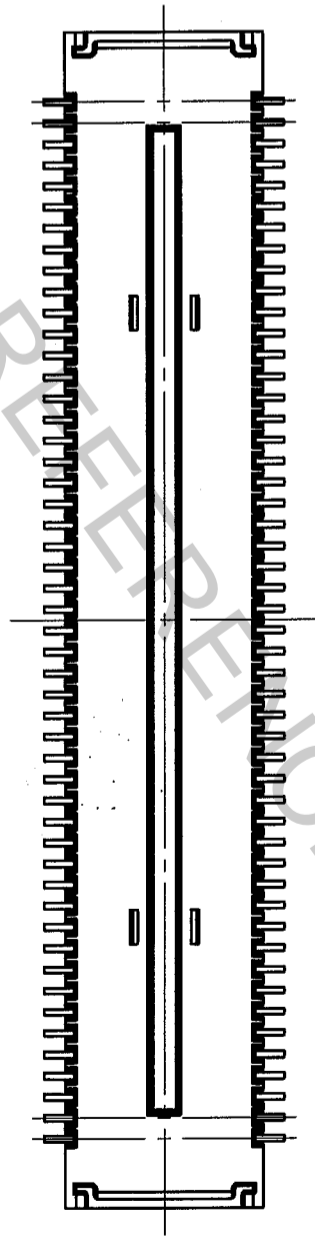
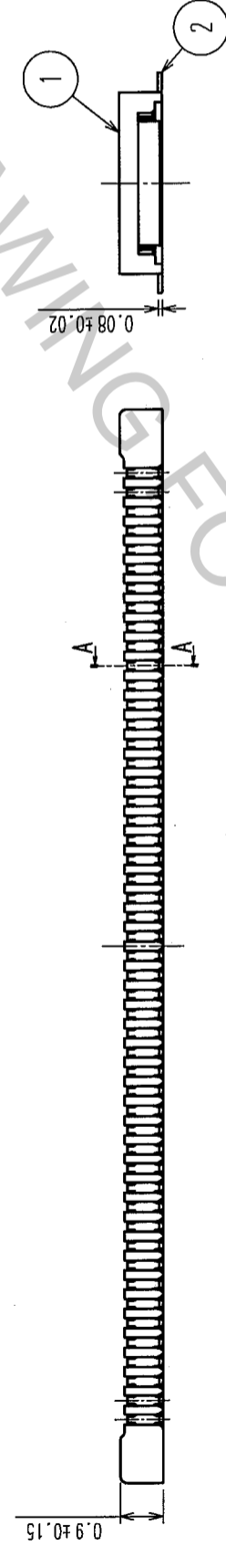


COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△					△				
△					△				
△					△				

RECOMMENDED PATTERN



RECOMMENDED SOLDER PASTE: THICKNESS 120 μm



PART NO.	CODE NO.	A	B	C
DF30FC-80DS-0.4V(82)	CL684-1116-3-82	18.22	15.6	3.2
DF30FC-70DS-0.4V(82)	CL684-1115-0-82	16.22	13.6	2.8
DF30FC-60DS-0.4V(82)	CL684-1082-3-82	14.22	11.6	2.4
DF30FC-50DS-0.4V(82)	CL684-1114-8-82	12.22	9.6	2
DF30FC-40DS-0.4V(82)	CL684-1078-6-82	10.22	7.6	1.6
DF30FC-34DS-0.4V(82)	CL684-1113-5-82	9.02	6.4	1.36
DF30FC-30DS-0.4V(82)	CL684-1112-2-82	8.22	5.6	1.2
DF30FC-24DS-0.4V(82)	CL684-1111-0-82	7.02	4.4	1.2
DF30FC-22DS-0.4V(82)	CL684-1110-7-82	6.62	4.0	1.2
DF30FC-20DS-0.4V(82)	CL684-1109-8-82	6.22	3.6	1.2

NOTE 1: ALL LEADS CO-PLANARITY SHALL BE 0.1 MAX.
 2. PER REEL : 1000 CONNECTORS.
 3. AT THE BEGINNING OF THE REEL, 100 MM AT MIN SHALL BE EMPTY POCKETS.
 AT THE END OF THE REEL, 160 MM AT MIN SHALL BE EMPTY POCKETS.
 NO CAVITY ON THE CONNECTORS LESS THAN 24 POS.
 CONTACT PLATING SPECIFICATIONS.
 CONTACT AREA : GOLD 0.05 μm MIN.
 SMT LEAD : GOLD 0.02 μm MIN.
 UNDERPLATING : NICKEL 1 μm MIN.
 (SURFACE : SEALING)

2	PHOSPHOR BRONZE	5	4	POLYESTER	CLEAR(COVER TAPE)
1	LCP	UL94V-0, BLACK	3	PS	CLEAR(EMBOSSED CARRIER TAPE)
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
CODE NO. (OLD)		DESIGNED	CHECKED	APPROVED	RELEASED
		T. NISHI	K. Mitsuhashi	J. Oga	
		040825	04.08.25	04.08.25	
DRAWING NO.		PART NO.			
EDC3-303556-05		DF30FC-*DS-0.4V(82)			
SCALE		CODE NO.			
FREE		CL684-***-*-82			
UNITS		HIROSE ELECTRIC CO., LTD			
mm					

